王金勝個人簡歷

Dr Wang received his Master and Doctorate in Chemical Engineering from National Taiwan University. He worked for Industrial Technology Research Institute (ITRI) from 1992 to 1997.

Jason Wang joined Unimicron since 1997 and devoted to IC substrate development for three years. Afterwards, he shifted to Subtron after Unimicron acquired this company in 2000. He served as the Vice President of Engineering in Subtron. He and his team focused on the development of substrates for the applications of RF and LED products in which the heat dissipation become more and more challenging. He and his team created many novel solutions and acquired many patents. He also has many years of experience and expertise in electroplating and surface finishing.

He was back to Unimicron in 2016 and started to take over R&D department of PCB II business division as senior Vice President from September of 2017. He and his team dedicated in the development of PCB for high speed and high frequency, high power applications. He is currently in charge of the New Business Development Division and Advanced Technology Development Center as VCTO.

演講摘要

未來電子產品將朝往更高頻高速的應用發展，頻率的上升及傳輸速度的增加對於IC 載板及印刷電路板的性能要求將越來越高。針對高段應用的先進 IC 載板與印刷電路板必須考慮到高頻高速的電氣特性及訊號完整性的需求，從疊構設計、材料選擇、製程技術尋求解決方案，兼顧產品性能、製造成本與可靠度。本演講除了介紹目前先進 IC 載板和印刷電路板的相關材料與製作技術及所遭遇的困難與挑戰之外，希望藉此演講機會吸引更多人才參與合作共創未來，內容包含:

1. 欣興電子介紹
2. 認識 IC 載板與印刷電路板
3. 材料與加工技術
4. 來自高頻高速應用的挑戰與機會
5. 問題討論與交流

Abstract

More and more electronic devices will be developed for applications of high-frequency or high-speed transmission to achieve higher data transfer rate and larger capacity in the future. Therefore, the requirements of the performance on the IC substrates and printed circuit boards (PCBs) become more and more stronger. To make advanced IC substrates and PCBs to fulfill the electrical performance and signal integrity for high-frequency or high-speed transmission, it needs to take into accounts their stack-up design, material selection and manufacturing technologies and optimize to get a solution compromising performance, manufacture cost and reliability. The challenges associated with fabrication of advanced IC substrates and PCBs will be illustrated, the opportunities will be addressed as well. We would like to invite more talents to join us to create a better future. The outlines of this lecture are:

1. **Introduction to Unimicron**
2. **Understand of IC Substrates and PCBs**
3. **Illustration of the Material and Manufacturing Process**
4. **Challenges and Opportunities from high-frequency and high-speed transmission**
5. **Discussion and Interaction**